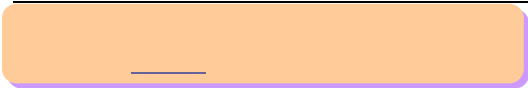


有铅

Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi

- | | | | |
|---|-------|---------------|-----|
| 1 | | 0.2mm | |
| 2 | | | 12 |
| 3 | | | |
| 4 | | | |
| 5 | | | |
| 6 | --- | | PCB |
| 7 | ICT | | |
| 8 | ----- | Paste in hole | |

		ROL1	J-STD-004
卤素		0.15wt%	
(SIR)		1 10 ¹³	25mil
		1 10 ¹²	40 90%RH 96Hrs
		1 10 ⁵	
			IPC-TM-650
			IPC-TM-650
			In house
		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		220 ± 30 Pa.s Malcolm (10rpm, 2)	T5, 89% metal for printing
		160 Pa.s ± 10% Malcolm (10rpm, 2)	T4, 87% metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate (Sn63, 90% metal)
			J-STD-005
			In house
Vs	48gF	0	IPC-TM-650 ± 5%
	56gF	2	
	68gF	4	
	44gF	8	
		12	In house
			0~10



1

T3 mesh -325/+500 25~45 m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 ⁰ ~ 60 ⁰
	2 ~ 4 10 ⁵ pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



*

*



*

PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

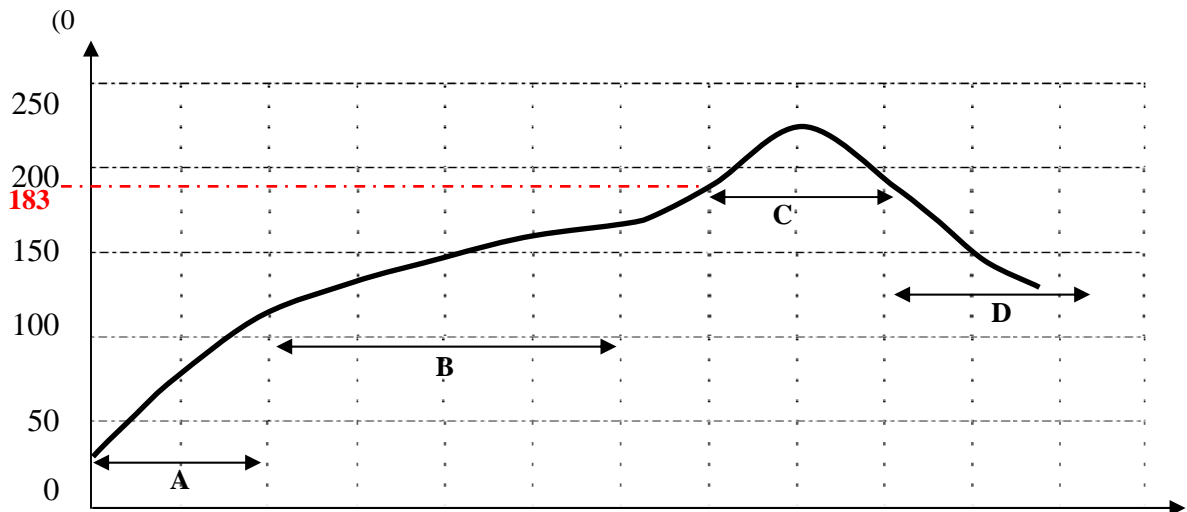
6



MSDS

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Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi



A. _____ 25~33%

* 1.0~3.0 /
*

B. _____ 33~50%

PCB
* 130~170 60~120 2 /

C. _____

* 210~240 183 40~90 Important 200 20~50
*
*

D. _____

* 4 75
*
*

